

2SD1747, 2SD1747A

Silicon NPN epitaxial planar type

For power switching

■ Features

- Low collector-emitter saturation voltage $V_{CE(sat)}$
- Satisfactory linearity of forward current transfer ratio h_{FE}
- Large collector current I_C
- I type package enabling direct soldering of the radiating fin to the printed circuit board, etc. of small electronic equipment

■ Absolute Maximum Ratings $T_C = 25^\circ\text{C}$

Parameter		Symbol	Rating	Unit
Collector-base voltage (Emitter open)	2SD1747	V_{CBO}	130	V
	2SD1747A		150	
Collector-emitter voltage (Base open)	2SD1747	V_{CEO}	80	V
	2SD1747A		100	
Emitter-base voltage (Collector open)		V_{EBO}	7	V
Collector current		I_C	7	A
Peak collector current		I_{CP}	15	A
Collector power dissipation		P_C	15	W
$T_a = 25^{\circ}\text{C}$			1.3	
Junction temperature		T_j	150	$^{\circ}\text{C}$
Storage temperature		T_{stg}	-55 to +150	$^{\circ}\text{C}$

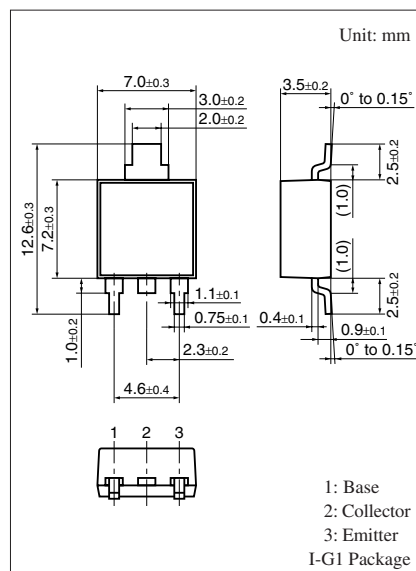
■ Electrical Characteristics $T_C = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-emitter voltage (Base open)	V_{CEO}	$I_C = 10\text{ mA}, I_B = 0$	80			V
			100			
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = 100\text{ V}, I_E = 0$			10	μA
Emitter-base cutoff current (Collector open)	I_{EBO}	$V_{EB} = 5\text{ V}, I_C = 0$			50	μA
Forward current transfer ratio	h_{FE1}	$V_{CE} = 2\text{ V}, I_C = 0.1\text{ A}$	45			—
	h_{FE2}^*	$V_{CE} = 2\text{ V}, I_C = 3\text{ A}$	90		260	
Collector-emitter saturation voltage	$V_{CE(sat)}$	$I_C = 5\text{ A}, I_B = 0.25\text{ A}$			0.5	V
Base-emitter saturation voltage	$V_{BE(sat)}$	$I_C = 5\text{ A}, I_B = 0.25\text{ A}$			1.5	V
Transition frequency	f_T	$V_{CE} = 10\text{ V}, I_C = 0.5\text{ A}, f = 10\text{ MHz}$		30		MHz
Turn-on time	t_{on}	$I_C = 3\text{ A}, I_{B1} = 0.3\text{ A}, I_{B2} = -0.3\text{ A}$ $V_{CC} = 50\text{ V}$		0.5		μs
Storage time	t_{stg}			1.5		μs
Fall time	t_f			0.2		μs

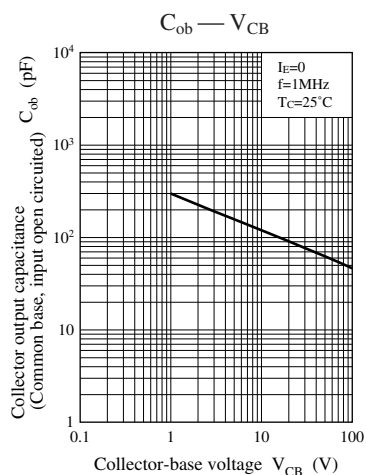
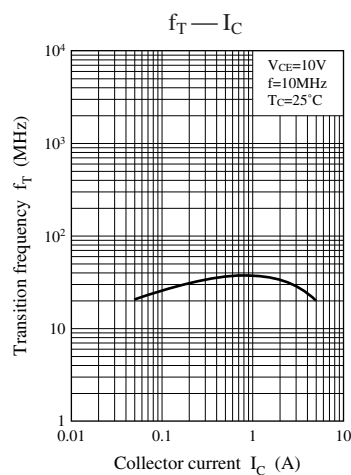
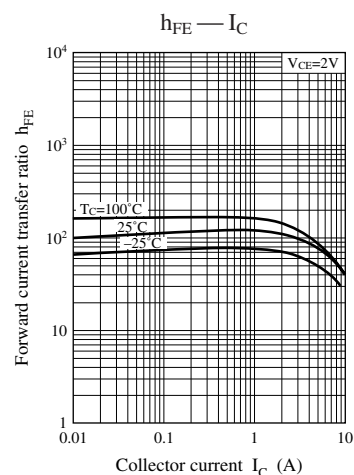
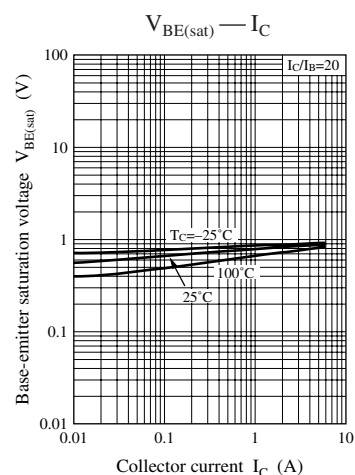
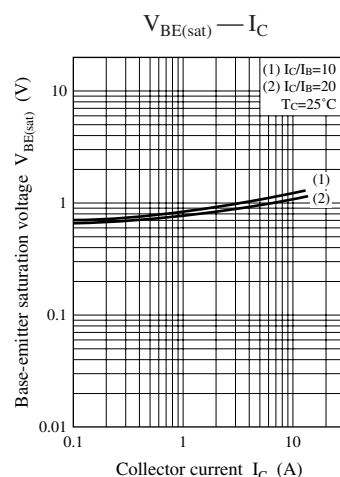
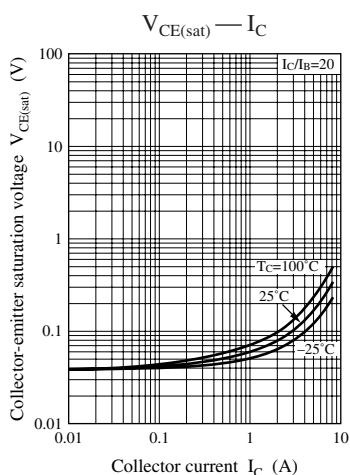
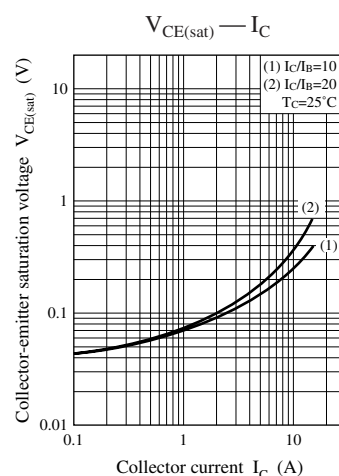
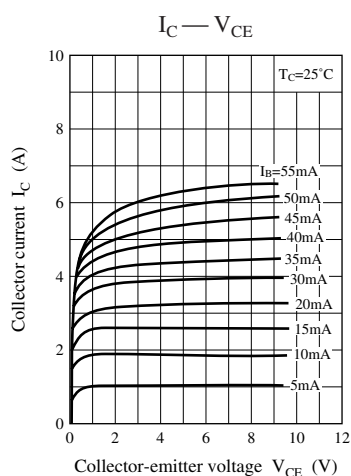
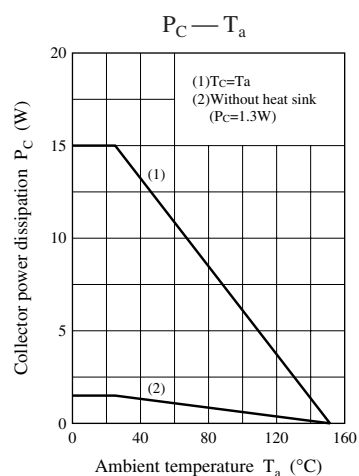
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

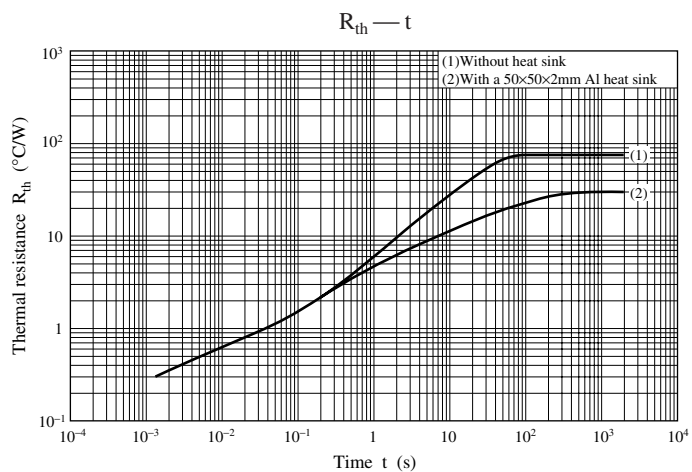
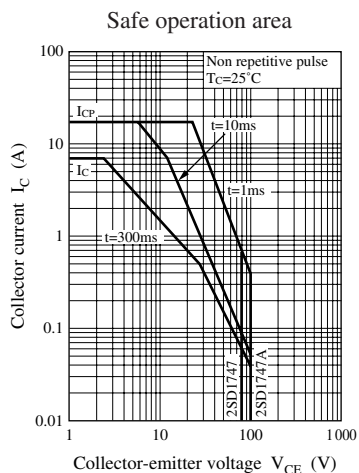
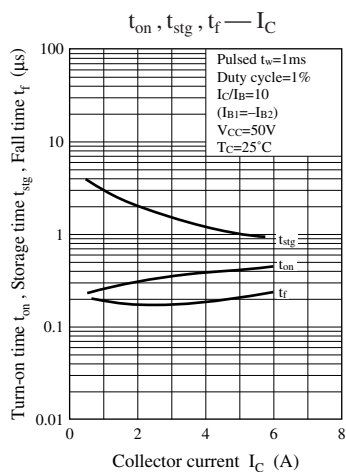
2. *: Rank classification

Rank	Q	P
h_{FE1}	90 to 180	130 to 260



Note) Self-supported type package is also prepared.





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